3.3V ECL Dual 1:4, 1:5 Differential Fanout Buffer

Description

The MC100LVE210 is a low voltage, low skew dual differential ECL fanout buffer designed with clock distribution in mind. The device features two fanout buffers, a 1:4 and a 1:5 buffer, on a single chip. The device features fully differential clock paths to minimize both device and system skew. The dual buffer allows for the fanout of two signals through a single chip, thus reducing the skew between the two fundamental signals from a part–to–part skew down to an output–to–output skew. This capability reduces the skew by a factor of 4 as compared to using two LVE111's to accomplish the same task.

To ensure that the tight skew specification is met it is necessary that both sides of the differential output are identically terminated, even if only one side is being used. In most applications all nine differential pairs will be used and therefore terminated. In the case where fewer than nine pairs are used it is necessary to terminate at least the output pairs adjacent to the output pair being used in order to maintain minimum skew. Failure to follow this guideline will result in small degradations of propagation delay (on the order of 10–20 ps) of the outputs being used, while not catastrophic to most designs this will result in an increase in skew. Note that the package corners isolate outputs from one another such that the guideline expressed above holds only for outputs on the same side of the package.

The MC100LVE210, as with most ECL devices, can be operated from a positive V_{CC} supply in PECL mode. This allows the LVE210 to be used for high performance clock distribution in +3.3 V systems. Designers can take advantage of the LVE210's performance to distribute low skew clocks across the backplane or the board. In a PECL environment series or Thevenin line terminations are typically used as they require no additional power supplies, if parallel termination is desired a terminating voltage of $V_{CC} - 2.0$ V will need to be provided. For more information on using PECL, designers should refer to Application Note AN1406/D.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

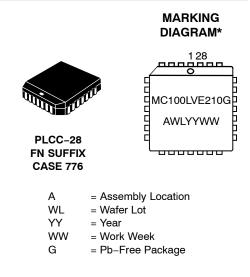
- 200 ps Part-to-Part Skew
- 50 ps Typical Output-to-Output Skew
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: $V_{CC} = 3.0$ V to 3.8 V with $V_{EE} = 0$ V
- NECL Mode Operating Range: $V_{CC} = 0$ V with $V_{EE} = -3.0$ V to -3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with Inputs Open or at V_{EE}
- Pb-Free Packages are Available*

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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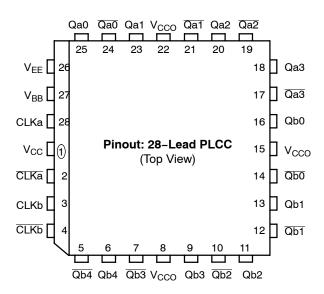
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*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

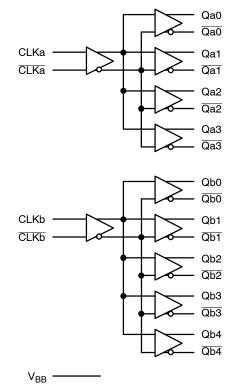


Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Pinout Assignment

Table 1. PIN DESCRIPTION

Pin	Function
CLKa, CLKa	ECL Differential Input Pairs
CLKb, CLKb	ECL Differential Input Pairs
Qa0:3, Qa0:3	ECL Differential Outputs
Qb0:3, Qb0:3	ECL Differential Outputs
V _{BB}	Reference Voltage Output
V _{CC} , V _{CCO}	Positive Supply
V _{EE}	Negative Supply



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Figure 2. Logic Diagram

Tab	le	2.	AT	TRI	BU	TES	

Characteristi	Value			
Internal Input Pulldown Resistor	50 kΩ			
Internal Input Pullup Resistor	N/A			
ESD Protection	> 2 kV > 200 V			
Moisture Sensitivity, Indefinite Time Ou	it of Drypack (Note 1)	Pb Pkg	Pb-Free Pkg	
	PLCC-28	Level 1	Level 3	
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
Transistor Count	13	79		
Meets or Exceeds JEDEC Standard El	A/JESD78 IC Latchup Test			

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V _{CC} = 0 V		–8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \leq V_{CC}$ $V_{I} \geq V_{EE}$	6 to 0 -6 to 0	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	PLCC-28 PLCC-28	63.5 43.5	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	PLCC-28	22 to 26 \pm 5%	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

			−40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current			55			55			65	mA
V _{OH}	Output HIGH Voltage (Note 3)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 3)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V_{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 7)	1.8		2.9	1.8		2.9	1.8		2.9	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

Table 4. LVPECL DC CHARACTERISTICS V_{CC} = 3.3 V; V_{FF} = 0.0 V (Note 2)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary \pm 0.3 V. 3. Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V.

4. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . V_{IHCMR} is defined as the range within which the V_{IH} level may vary, with the device still meeting the propagation delay specification. The V_{IL} level must be such that the peak to peak voltage is less than 1.0 V and greater than or equal to V_{PP}(min).

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current			55			55			65	mA
V _{OH}	Output HIGH Voltage (Note 6)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 6)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
VIH	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V _{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 7)	-1.5		-0.4	-1.5		-0.4	-1.5		-0.4	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

Table 5. LVNECL DC CHARACTERISTICS $V_{CC} = 0.0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 5)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary ±0.3 V. 6. Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V. 7. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} . V_{IHCMR} is defined as the range within which the V_{IH} level may vary, with the device still meeting the propagation delay specification. The V_{IL} level must be such that the peak to peak voltage is less than 1.0 V and greater than a specification. or equal to VPP(min).

			-40°C		25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency		700			700			700		GHz
t _{PLH} t _{PHL}	Propagation Delay to Output IN (Differential) (Note 9) IN (Single-Ended) (Note 10)	475 400		675 700	500 450		700 750	500 450		700 750	ps
t _{skew}	Within-Device Skew (Note 11) Qa to Qb Qa to Qa, Qb to Qb Part-to-Part Skew (Diff)		50 50	75 75 200		50 30	75 50 200		50 30	75 50 200	ps
t _{JITTER}	Cycle-to-Cycle Jitter		< 1			< 1			< 1		ps
V _{PP}	Input Swing (Note 12)	500		1000	500		1000	500		1000	mV
t _r /t _f	Output Rise/Fall Time (20%-80%)	200		600	200		600	200		600	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

8. V_{EE} can vary ±0.3 V.

9. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals.

10. The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the crossing point of the differential output signals.

11. The within-device skew is defined as the worst case difference between any two similar delay paths within a single device.

12. V_{PP}(min) is defined as the minimum input differential voltage which will cause no increase in the propagation delay. The V_{PP}(min) is AC limited for the LVE210 as a differential input as low as 50 mV will still produce full ECL levels at the output.

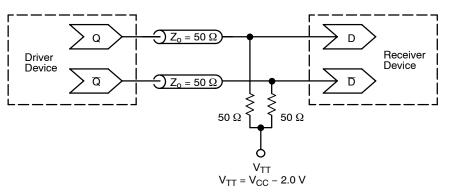


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100LVE210FN	PLCC-28	37 Units / Rail
MC100LVE210FNG	PLCC-28 (Pb-Free)	37 Units / Rail
MC100LVE210FNR2	PLCC-28	500 Tape & Reel
MC100LVE210FNR2G	PLCC-28 (Pb-Free)	500 Tape & Reel

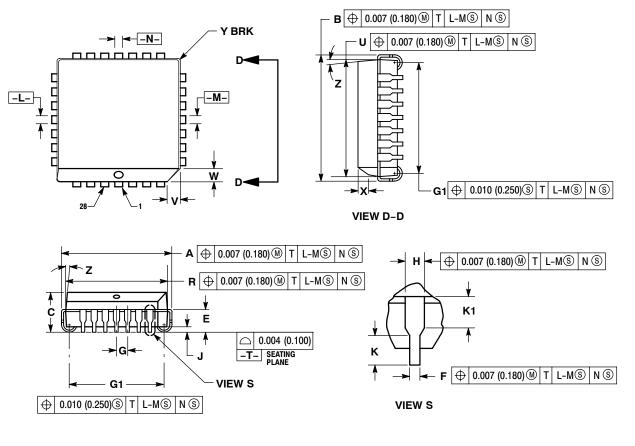
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	-	Designing with PECL (ECL at +5.0 V)
AN1503/D	-	ECLinPS [™] I/O SPiCE Modeling Kit
AN1504/D	-	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1642/D	-	The ECL Translator Guide
AND8001/D	-	Odd Number Counters Design
AND8002/D	-	Marking and Date Codes
AND8020/D	_	Termination of ECL Logic Devices
AND8066/D	_	Interfacing with ECLinPS
AND8090/D	_	AC Characteristics of ECL Devices

PACKAGE DIMENSIONS





NOTES:

- 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS

- WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI VIA EM 1982
- ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, THE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC POPY
- BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY. 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.485	0.495	12.32	12.57	
В	0.485	0.495	12.32	12.57	
С	0.165	0.180	4.20	4.57	
Е	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
ſ	0.020		0.51		
Κ	0.025		0.64		
R	0.450	0.456	11.43	11.58	
U	0.450	0.456	11.43	11.58	
۷	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Χ	0.042	0.056	1.07	1.42	
Y		0.020		0.50	
Z	2 °	10°	2 °	10°	
G1	0.410	0.430	10.42	10.92	
K1	0.040		1.02		

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